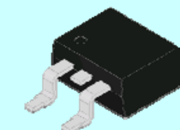
FAGOR
Fagor Electrónica, S. Coop.

MATERIAL COMPOSITION DECLARATION

Date: 09.02.2007

Supplier: Fagor Electrónica S. Coop



Package: D2PAK

Part Number:

Description: SCR's and Triacs

COMPOSITION PART	MATERIAL NAME	MATERIAL MASS(mg)	MATERIAL MASS(%)	ELEMENT NAME COMPOSITION	CAS Nº	ELEMENT % (BY WEIGHT)	Cd (ppm)	Pb (ppm)	Hg (ppm)	Cr 6+ (ppm)	PBBs (ppm)	PBDEs (ppm)
LEAD FRAME	Cu alloy	219,030	15,09%	Cu Fe P	7440-508 7439-896 7723-140	99,87 0,1 0,03	<5	12	<5	<5	<5	<5
ENCAPSULATION	Epoxy	1098,600	75,69%	Fused silica Polyglycidiyl Ether O-cresol Formaldehyde Novolac Brominated Epoxy resin Antimony oxide Carbon black	60676-86-0 29690-82-2 40039-93-8 1309-64-4 1333-86-4	70-75 10-15 1-3 1-3 1-3	<5	12	<5	<5	<5	<5
CHIP	Doped Silicon Glass Passivated	7,350	0,51%	Si Al Ni SiO2 PbO Al2O3	7440-213 7429-90-5 7440-02-0 7631-86-9 1317-36-8 1344-28-1	90,7-92,1 1,7-2,2 0,8-1,2 2,7-2,9 2,5-2,7 0,2-0,3	< 1	< 10 24100 (**)	< 0,5	< 10	< 200	< 200
DIE BONDING MATERIAL	Solder Wire	8,560	0,59%	Pb Sn Ag	7489-92-1 7440-31-5 7440-22-4	95 2,5 2,5	<5	950000 (*)	<5	<5	<5	<5
WIRES	Aluminum	3,170	0,22%	Al	7429-90-5	100	<5	12	<5	<5	<5	<5
COATING	Sn	114,790	7,91%	Sn	7440-31-5	100	<5	12	<5	<5	<5	<5
WHOLE ITEM		1451,500	100,00%									

Exception according to annex of Directive 2002/95/EC (RoHS):

* Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85% lead)

MONDRAGON COMPONENTES

** Lead in glass of cathode ray tubes, electronic componentes and fluorescent tubes